

Title: HEEET COMPOSITE CARRIER STRUCTURE

Solicitation: NNA15543122R-AMD

Questions and Answers - Set 1

1. Question: Do you foresee needing more than two assemblies in the future? Are you open to the use of disposable tooling?
 - Answer: NASA does not see the need for additional carrier structures of this specific size. NASA is open to adopt manufacturing methodologies that reduce cost.
2. Question: What are the NDI requirements for the Carrier Forebody Shell?
 - Answer: NDI requirements are listed in section 7.5 of HEEET-4009. Options for most practical utilization of NDI techniques given the size and shape of the carrier Forebody Shell would be valuable.
3. Question: Are the Mandatory Inspection Points in Section 7.1.3 of HEEET-4009 in person or over the phone?
 - Answer: Mandatory Inspection Points are in person.
4. Question: Could you provide a 3D model for the Carrier Ring in STEP format?
 - Answer: Not at this time.
5. Question: Would you accept a single lump price for Phase 0 or must we price these line items separately?
 - Answer: The manufacturing approach anticipated by NASA would be to cut all coupon substrates from a single larger panel. Given this methodology a single lump price for Phase 0 would be acceptable.

End of Questions and Answers - Set 1